

L Number	Hits	Search Text	DB	Time stamp
1	142010	(silicon or lens or mirror) same pattern\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:28
2	7285	((silicon or lens or mirror) same pattern\$3) same (polish\$3 or planariz\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:21
3	4238	((silicon or lens or mirror) same pattern\$3) same (polish\$3 or planariz\$3)) and (dic\$3 or slic\$3 or separat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:23
4	2734	((silicon or lens or mirror) same pattern\$3) same (polish\$3 or planariz\$3)) and (dic\$3 or slic\$3 or separat\$3)) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:00
5	14	((silicon or lens or mirror) same pattern\$3) same (polish\$3 or planariz\$3)) and (dic\$3 or slic\$3 or separat\$3)) and @pd<20011108) and (micro near mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:25
6	84907	silicon same pattern\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:37
7	6233	(silicon same pattern\$3) same (polish\$3 or planariz\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:39
8	3724	((silicon same pattern\$3) same (polish\$3 or planariz\$3)) and (dic\$3 or split\$3 or separat\$3 or slic\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:30
9	8	((silicon same pattern\$3) same (polish\$3 or planariz\$3)) and (dic\$3 or split\$3 or separat\$3 or slic\$3)) and (blind near hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:31
10	811	(silicon same topograph\$2) same pattern\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:38
11	150	((silicon same topograph\$2) same pattern\$3) and (rough\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:39
12	109	((silicon same topograph\$2) same pattern\$3) and (rough\$4)) and (polish\$3 or planariz\$3 or "CMP")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:39
13	72	((silicon same topograph\$2) same pattern\$3) and (rough\$4)) and (polish\$3 or planariz\$3 or "CMP")) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 10:33

14	35	((((silicon same topograph\$2) same pattern\$3) and (rough\$4)) and (polish\$3 or planariz\$3 or "CMP")) and @pd<20011108) and (lens or mirror or optical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 10:33
19	2976	(silicon same hole) same (polish\$3 or planariz\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:10
20	274	((silicon same hole) same (polish\$3 or planariz\$3)) and topograph\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 10:59
21	194	((silicon same hole) same (polish\$3 or planariz\$3)) and topograph\$2) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:03
22	6233	(silicon same pattern\$3) same (polish\$3 or planariz\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:12
23	32262	(silicon or wafer same pattern\$3) same (polish\$3 or planariz\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:12
24	4106	((silicon same pattern\$3) same (polish\$3 or planariz\$3)) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:47
25	496	((silicon same pattern\$3) same (polish\$3 or planariz\$3)) and @pd<20011108) and (lens or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:15
26	380	((((silicon same pattern\$3) same (polish\$3 or planariz\$3)) and @pd<20011108) and (lens or mirror)) and (silicon same etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:17
27	66	((((silicon same pattern\$3) same (polish\$3 or planariz\$3)) and @pd<20011108) and (lens or mirror)) and (silicon same etch\$3)) and topograph\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:27
28	145907	silicon same (pattern\$3 or etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:32
29	15443	(silicon same (pattern\$3 or etch\$3)) same (polish\$3 or planariz\$3 or "CMP")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:46
30	20545	((silicon same (pattern\$3 or etch\$3)) same (polish\$3 or planariz\$3 or "CMP")) (surface near topograph\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 11:47

31	13860	((silicon same (pattern\$3 or etch\$3)) same (polish\$3 or planariz\$3 or "CMP")) (surface near topograph\$2)) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:01
32	755	(polish\$3 or planariz\$3) same (silicon same topograph\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 13:16
33	536	((polish\$3 or planariz\$3) same (silicon same topograph\$2)) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:19
34	21	((polish\$3 or planariz\$3) same (silicon same topograph\$2)) and @pd<20011108 and dic\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:05
35	30258	(polish\$3 or planariz\$3) same (silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:13
36	12899	((polish\$3 or planariz\$3) same (silicon)) same etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:15
37	1499	((polish\$3 or planariz\$3) same (silicon)) same etch\$3 and (dic\$3 or saw\$3 or cleav\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:16
38	1002	((((polish\$3 or planariz\$3) same (silicon)) same etch\$3) and (dic\$3 or saw\$3 or cleav\$3)) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:27
39	244	(etch\$3 same silicon) same(polish\$3 same (project\$3 or pillar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 12:30
40	158	((etch\$3 same silicon) same(polish\$3 same (project\$3 or pillar))) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 13:13
55	109	(polish\$3 or planariz\$3) same (silicon same topograph\$2) and (lens or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 13:18
56	13	ahmed-shamim.xa. and porous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 14:21
57	14042	silicon same (topograph\$2 or rough\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 15:17

58	1	(silicon same (topograph\$2 or rough\$4)) and (cur\$3 near optical near surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 14:24
59	1738	(silicon same (topograph\$2 or rough\$4)) and (micro near lens or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 15:18
60	1018	((silicon same (topograph\$2 or rough\$4)) and (micro near lens or mirror)) and (polish\$3 or planariz\$3 or "CMP")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 15:19
61	696	(((silicon same (topograph\$2 or rough\$4)) and (micro near lens or mirror)) and (polish\$3 or planariz\$3 or "CMP")) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 16:08
62	201	(((silicon same (topograph\$2 or rough\$4)) and (micro near lens or mirror)) and (polish\$3 or planariz\$3 or "CMP")) and @pd<20011108) and (dic\$3 or cutt\$3 or slic\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 16:47
63	13	((((silicon same (topograph\$2 or rough\$4)) and (micro near lens or mirror)) and (polish\$3 or planariz\$3 or "CMP")) and @pd<20011108) and (dic\$3 or cutt\$3 or slic\$3)) and (anti near reflect\$3 or reflect\$3 near coat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 16:55
64	18435	(silicon same etch\$3) same hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:00
65	2108	((silicon same etch\$3) same hole) same (polish\$3 or grind\$3 or planariz\$3 or "CMP")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:03
66	193	((silicon same etch\$3) same hole) same (polish\$3 or grind\$3 or planariz\$3 or "CMP")) and (lens or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:10
67	92	(((silicon same etch\$3) same hole) same (polish\$3 or grind\$3 or planariz\$3 or "CMP")) and (lens or mirror)) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:23
70	335	(etch\$3 same glass) same topograph\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:24
71	267	((etch\$3 same glass) same topograph\$2) and @pd<20011108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:26
72	192	(((etch\$3 same glass) same topograph\$2) and @pd<20011108) and (polish\$3 or planariz\$3 or grind\$3 or lapp\$3 or "CMP")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:27